

HSP Series Thermal Pads



- Easy-to-use thermal interface Material designed for use with Standard Crydom single-phase and three-phase solid-state relays.
- Excellent alternative to thermal grease
- Adhesive on one side

HSP-2

For use with all single phase Panel mount SSR's, Control modules and M50 power modules.

HSP-5

For use with all three phase panel mount SSR's (53TP/53RV).

HSP-6

For use with EL Series panel mount SSR's.

TYPICAL PROPERTIES

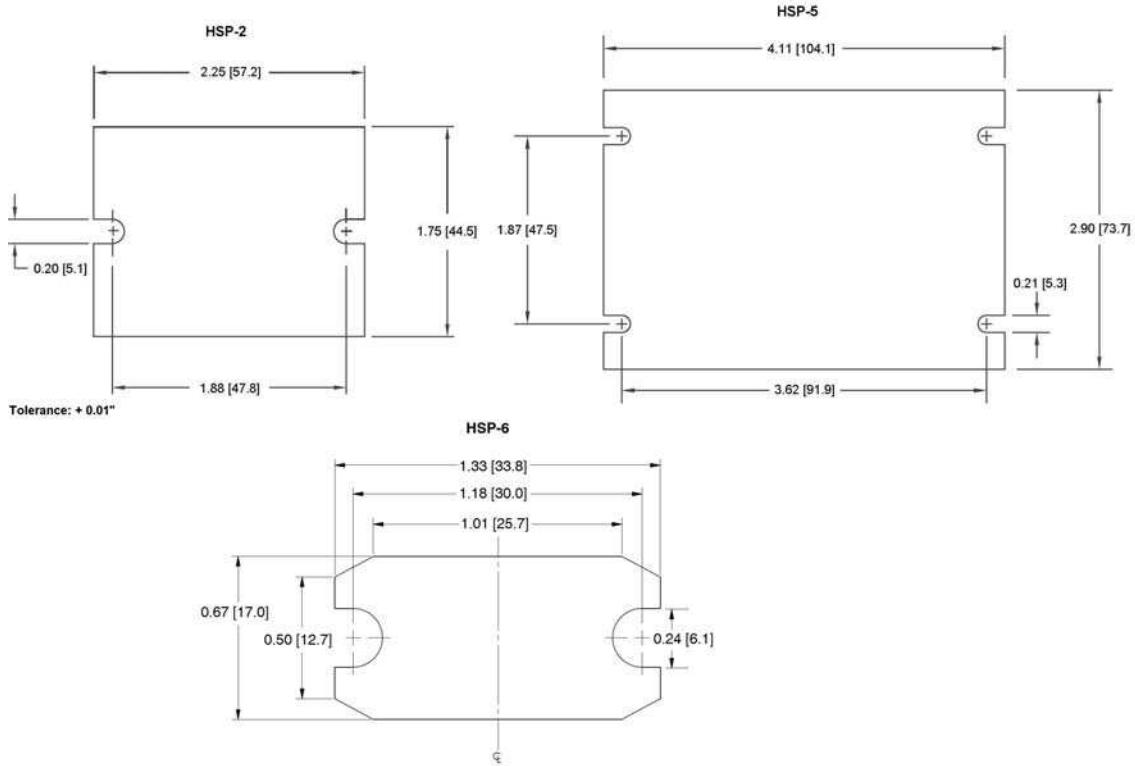
Description	HSP-2/HSP-5/HSP-6
Color	Black
Thickness, inch (mm)	0.005 (0.127)
Adhesive One Side	Yes
Thermal Impedance [°C-in ² /W] (1)	0.48 @25 psi
Thermal Conductivity [W/m-K]	2.0
Flame Rating	V-0
Continuous Temperature Range [°C]	-60 to 180
Volume Resistivity [ohm-cm]	10 ² Ohm

NOTES

- (1) This value is provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

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MECHANICAL SPECIFICATIONS



ANNEX - ENVIROMENTAL INFORMATION

The environmental information disclosed in this annex including the EIP Pollution logo are in compliance with People's Republic of China Electronic Industry Standard SJ/T11364 – 2006, Marking for Control of Pollution Caused by Electronic Information Products.

Part Name	Toxic or hazardous Substance and Elements					
	Lead (Pb)	Mercury (Hg)	Cadmium (Cd)	Hexavalent Chromium (Cr (VI))	Polybrominated biphenyls (PBB)	Polybrominated diphenyl ethers (PBDE)
Semiconductor die	X	O	O	O	O	O
Solder	X	O	O	O	O	O

此附件所标示的包括电子信息产品污染图标的环保信息符合中华人民共和国电子行业标准 **SJ/T11364 - 2006**, 电子信息产品污染控制标识要求



部件名称	有毒有害物质或元素					
	铅 (Pb)	汞 (Hg)	镉 (Cd)	六价铬 (Cr (VI))	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
半导体芯片	X	O	O	O	O	O
焊接点	X	O	O	O	O	O